

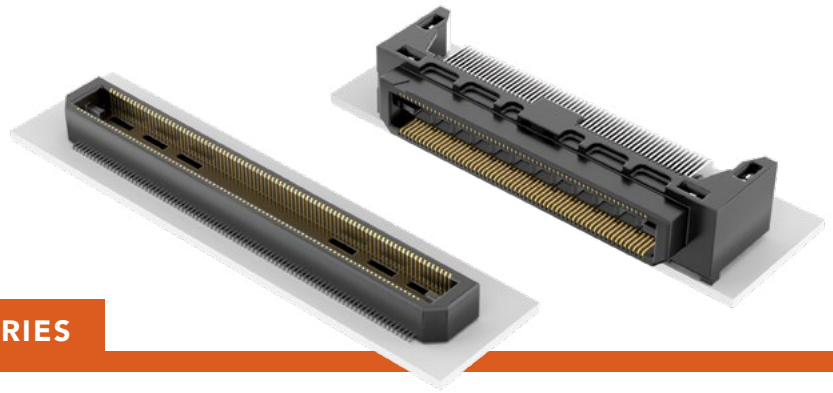


**THE DATASHEET OF
BTH-090-01-L-D-A**



BASIC BLADE & BEAM HEADER

(0.50 mm) .0197" PITCH • BTH SERIES



BTH

Mates:

BSH

SPECIFICATIONS

Insulator Material:

Black LCP

Contact Material:

Phosphor Bronze

Plating:

Au or Sn over
50 μ" (1.27 μm) Ni

Current Rating:

2.0 A per pin
(2 pins powered)

Operating Temp Range:

-55 °C to +125 °C

Voltage Rating:

175 VAC

Max Cycles:

100

PROCESSING

Lead-Free Solderable:

Yes

SMT Lead Coplanarity:

Vertical=

(0.10 mm) .004" max (030-090),

(0.15 mm) .006" max (120-150)*

Right-angle=

(0.15 mm) .006" max (030-090)*

*(.004" stencil solution

may be available; contact

ipg@samtec.com)

Board Stacking:

For applications requiring more

than two connectors per board

or 90 positions or higher,

contact ipg@samtec.com

ALSO AVAILABLE

MOQ Required

30 μ" (0.76 μm) Gold

Edge Mount Capability

8 mm, 11 mm, 16 mm,

19 mm and 22 mm Stack

Height (Caution: Some

automatic placement/

inspection machines may

have component height

restrictions. Please consult

machinery specifications.)

(11 mm, 16 mm, 19 mm

and 22 mm not available

with 50 positions)



Note:

Some lengths, styles and

options are non-standard,

non-returnable.

BTH	-	NO. OF POSITIONS PER ROW	-	01	-	PLATING OPTION	-	D	-	A	-	OTHER OPTION
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-030, -050, -060,
-090, -120, -150

-F

= Gold Flash
on contact,
Matte Tin on tail

-L

= 10 μ" (0.25 μm)
Gold on contact,
Matte Tin on tail

-C*

= Electro-Polished Selective
50 μ" (1.27 μm) min
Au over 150 μ" (3.81 μm)
Ni on Signal Pins in contact
area, Matte Tin over
50 μ" (1.27 μm) min
Ni on all solder tails
(*C Plating passes
10 year MFG testing)

-K

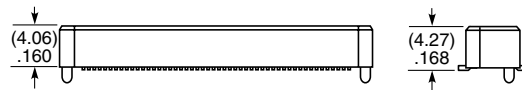
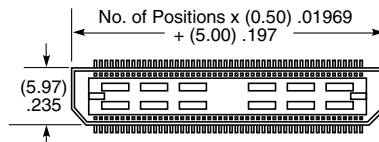
= (7.00 mm) .276"
DIA Polyimide
Film Pick
& Place Pad

-TR

= Tape & Reel
(120 positions
maximum)

-FR

= Full Reel
Tape & Reel
(must order
maximum
quantity per reel;
contact
Samtec for
quantity breaks)
(120 positions
maximum)



MATED HEIGHT

LEAD STYLE	MATED HEIGHT*
-01	(5.00 mm) .1971"

*Processing conditions will affect mated height.

BTH	-	NO. OF POSITIONS PER ROW	-	01	-	PLATING OPTION	-	D	-	RA	-	WT	-	OTHER OPTION
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-030, -060, -090

-F

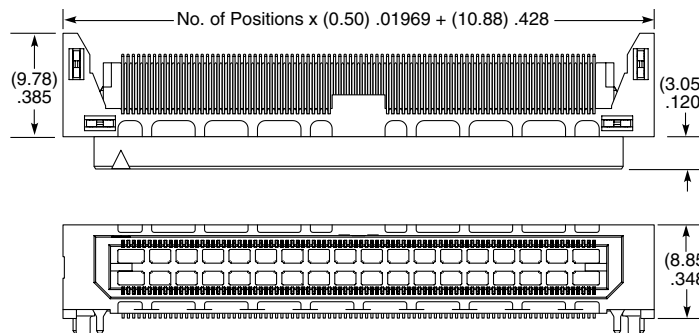
= Gold Flash on
contact, Matte
Tin on tail

-L

= 10 μ" (0.25 μm)
Gold on contact,
Matte Tin on tail


-K

= (7.00 mm)
.276" DIA
Polyimide
Film Pick &
Place Pad



Looking for pricing, stock, or lifecycle information?

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-  Cost Control Management
-  Shortage Management
-  Alternative Solution
-  Excess Inventory Management